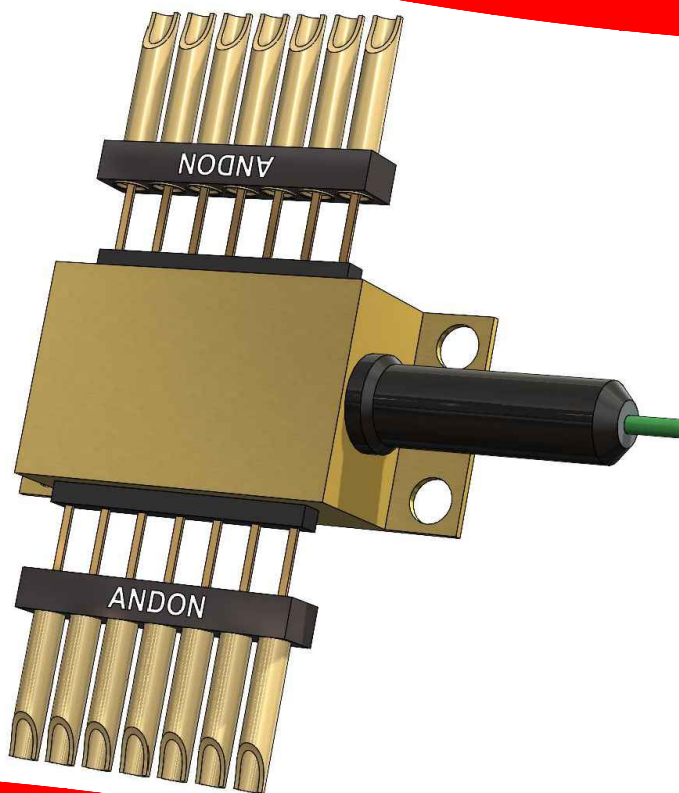




High-Reliability Optoelectronic Sockets for RPMC Lasers, Inc.



Featuring Andon's Unique SenstacTM Contact

RPMC						
RPMC Part Number	Andon Part Number Replace "XXX" With terminal Type	Terminal Type		Pin Ø [in]	Figure Number	Page Number
		Thru-Hole	Surface Mount			
Pulsed TO56	R100-0403-06T-XXX -R27-L14	75S	93S	0.018	1	1
TO9 - Capped	R100-0403-06T-XXX -R27-L14	75S	93S	0.018	1	1
TO9 - No Cap	R100-0403-06T-XXX -R27-L14	75S	93S	0.018	1	1
TO9 - Single Mode	R100-0403-06T-XXX -R27-L14	75S	93S	0.018	1	1
TO9 - Lensed Capped	R100-0403-06T-XXX -R27-L14	75S	93S	0.018	1	1
Triple Junction TO56 - Capped	R100-0403-06T-XXX -R27-L14	75S	93S	0.018	1	1
Triple Junction TO56 - No Cap	R100-0403-06T-XXX -R27-L14	75S	93S	0.018	1	1
14 Pin Single Mode Butterfly	C10-007-07-01-XXX-R27-L14	560VE	N/A	0.030	2	1
14 Pin DF	C10-007-07-01-XXX-R27-L14	627E	N/A	0.030	2	1
2CM	C486-002-02-02-XXX-R27-L14	608P55	N/A	0.062	3	1
	C10-006-06-01-XXX-R27-L14	627E	N/A	0.030		
15 Pin Fiber Module	C10-008-08-01-XXX-R27-L14	627E	N/A	0.030	4	1
	C10-008-07-01-XXX-R27-L14	627E	N/A	0.040		

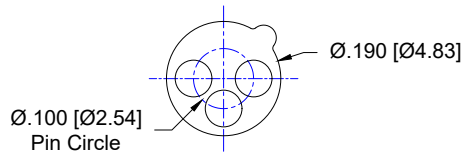


FIG: 1

Thru-Hole: R100-0403-06T-**75S**-R27-L14

Surface Mount: R100-0403-06T-**265S**-R27-L14

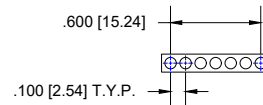
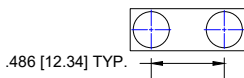


FIG: 2

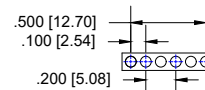
SOLDER CUP: C10-007-07-01-**627E**-R27-L14

2CM

FIG: 3



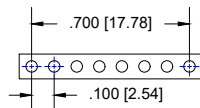
SOLDER CUP: C486-002-02-02-**608P55**-R27-L14



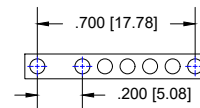
SOLDER CUP: C10-006-06-01-**627E**-R27-L14

15 Pin Fiber Module

FIG: 4



SOLDER CUP: C10-008-08-01-**627E**-R27-L14

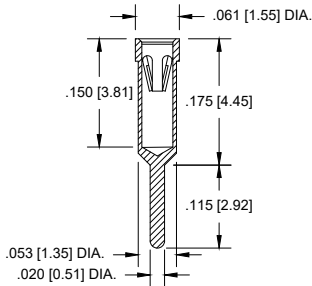


SOLDER CUP: C10-008-07-01-**627E**-R27-L14

RPMC Lasers Continued Socket Terminal Details Cross Section View Shown Units: in [mm] Other Terminal Layouts and Configurations available

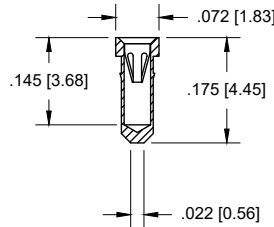
THRU HOLE OPTION

-75S



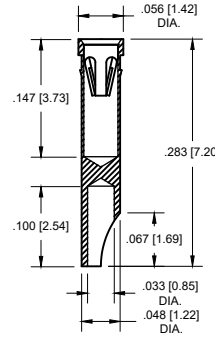
SURFACE MOUNT OPTION

-93S

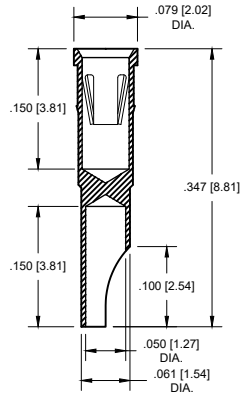


SOLDER - CUP OPTION

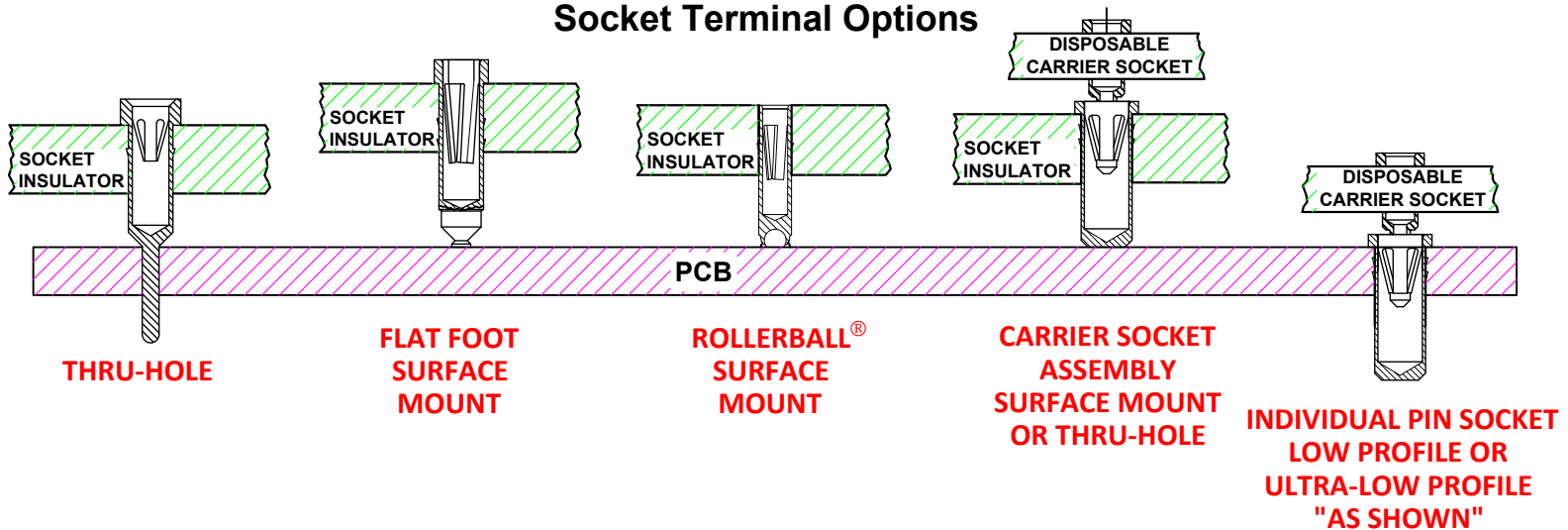
-627E



-608P55



Socket Terminal Options



Technical Information

Material:

Insulator: Hi-Temp UL 94V-O
Terminal: Brass, per ASTM-B16
Contact: BeCu, Per ASTM-B194

Plating: RoHS COMPLIANT

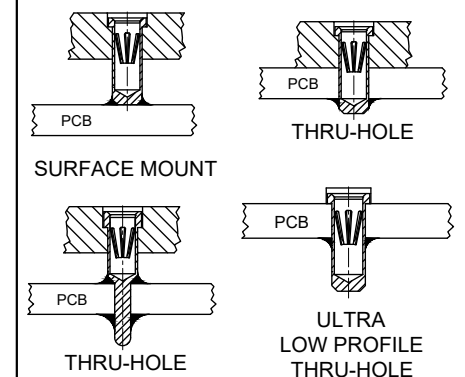
R27 TERMINAL: GOLD / CONTACT: GOLD

R17 TERMINAL: TIN / CONTACT: GOLD

OTHER PLATINGS AVAILABLE

Terminal Acceptance and Forces							
Thru Hole Terminals				Surface Mount Terminals			
Thru Hole Terminal	Accepts Pin Diameter	Insertion Force	Withdrawal Force	surface mount Terminal	Accepts Pin Diameter	Insertion Force	Withdrawal Force
75S	0.018 [ø0.46]	9.0 OZ AVG.	2.0 OZ MIN.	93S	0.018 [ø0.46]	9.0 OZ AVG.	2.0 OZ MIN.
627E	0.040 [ø1.02]	9.0 oz AVG.	2.0 OZ MIN.	N/A	N/A	N/A	N/A
608P55	0.060 [ø1.52]	15.5 oz Max	2.1 oz Min	N/A	N/A	N/A	N/A

MOUNTING OPTIONS



©Copyright 2024 Andon Electronics Corporation. All Rights Reserved. This material is protected under US and other copyrights and may not be copied, sold, or redistributed in any form without written permission of Andon Electronics Corporation. Copyrights and trademarks are property of their respective companies. We reserve the right to change specifications without notice. Andon makes no warranty, expressed or implied, as to the suitability of the sockets for the intended purpose.

"ANDON PROPRIETARY INFORMATION"

RoHS Compliant

*Sockets are not drawn to scale RPMC Lasers, Inc. 6/12/2024

For fast, accurate placement of SIP sockets and ultra-low profile terminals

Phase 1:
Receive Carrier Assemblies
designed to your pin layout.



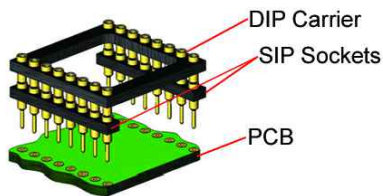
Phase 2:
Place carrier assemblies onto PCB;
run through your soldering process.



Phase 3:
Remove carrier and plug in your device;
discard carrier.

DIP

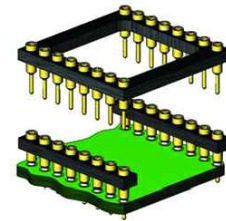
Before Soldering



During Soldering

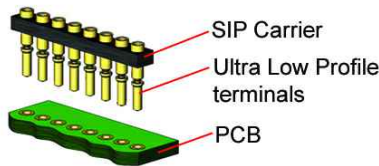


After Soldering



ULTRA-LOW PROFILE SIP

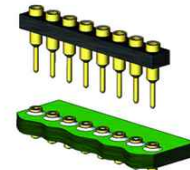
Before Soldering



During Soldering

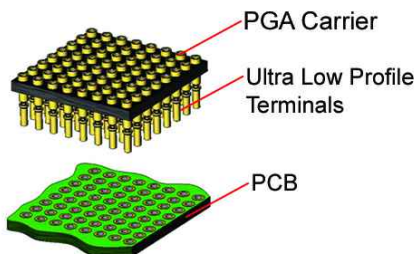


After Soldering



ULTRA-LOW PROFILE PGA

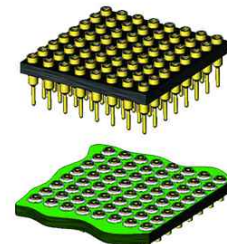
Before Soldering



During Soldering

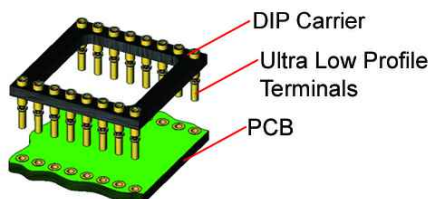


After Soldering

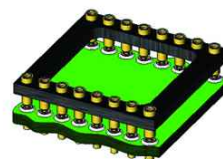


ULTRA LOW PROFILE DIP

Before Soldering



During Soldering



After Soldering

